EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	("5736074" | "6114187").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:05
S2	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:59
S3	7	("20040036200" | "20040099983" | "20040145088" | "20040207123" | "20050012247" | "6572807" | "7120512").PN. OR ("7329379").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 15:47
S4	178591	(fluid or solvent or resin or polymer or (metal near4 paste)) near7 (eject$4 or dropping or deposit$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S5	3793762	(substrate or wafer or pad)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S6	83637	S4 and S5	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:53
S7	3139993	(voltage or charage or (electric near4 field) or (electrostatic))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54

S8	37057	S6 and S7	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:54
S9	1161081	(nozzle or printhead or ink $4jet$4 or stereolithograph $4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S10	12179	S8 and S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S11	157	(solidifying) near5 (S4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:55
S12	0	246/401.ccls. and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:56
S13	314	425/174.2.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 15:57
S14	20602	(freeform near4 fabrication) (stereolithography) (rapid near3 prototyping) (solid near2 fabrication) (solid near2 lithography) (((three near3 dimensional) or 3D) near5 (print$3 or ink $4print))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:43
S15	532063	(solid$4 near5 (drop$3 or material or resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44

S16	4265	S14 and S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S17	349	264/401.ccls. and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:44
S18	81675	(stack$4) near6 (droplet or material)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S19	26	S17 and S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 16:58
S20	11	voltage and S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:02
S21	2	(nozzle or ink$4head or ink $4print) and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:03
S22	10	fluid and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:05
S23	41	("4575330" | "4752352" | "4863538" | "4999143" | "5015312" | "5058988" | "5059021" | "5076974" | "5104592" | "5121329" | "5123734" | "5133987" | "5141680" | "5143663" | "5174931" | "5182056" | "5182715" | "5184307" | "5192469" | "5192559" | "5204055" | "5209878" | "5234636" | "5238639" | "5256340" | "5321622" |	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 17:05

		"5597520" | "5840239" | "5902537" | "5902538" | "5943235" | "5945058" | "5965079" | "5999184" | "6001297").PN. OR ("6126884").URPN.				
S24	20086	264/401.ccls. (depositing and stacking)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S25	919	S14 and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S26	246	(solidifying) and S25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 17:12
S27	766	264/401.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S28	3793762	substrate or wafer or pad	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:27
S29	4999418	AC or DC or (direct near3 current) or (alternating near3 current) or voltage or electrostatic or (electric near3 field) or (charge)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S30	66	S27 and S28 and S29	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29
S31	28	(droplet or solder) and S30	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 08:29

| S33 | 173792 | ((substrate or wafer or pad) near2 heat$2) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/01 08:30 |
| S34 | 3 | S31 and S33 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/07/01 08:31 |

7/2/2009 2:33:37 PM
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